



DMP2004DMK

Features

- Dual P-Channel MOSFET
- Low On-Resistance
- Very Low Gate Threshold Voltage V_{GS(TH)} < 1V
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0

DUAL P-CHANNEL ENHANCEMENT MODE MOSFET

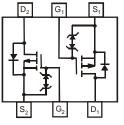
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.015 grams (Approximate)





SOT26

Top View



Top View Internal Schematic

Ordering Information (Note 4)

| Part Number | Case | Packaging |
|--------------|-------|------------------|
| DMP2004DMK-7 | SOT26 | 3000/Tape & Reel |

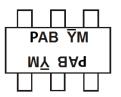
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

See http://www.diode and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



 $\begin{array}{l} PAB = Marking \ Code \\ \overline{YM} = Date \ Code \ Marking \\ Y \ or \ \overline{Y} = Year \ (ex: \ D = 2016) \\ M = Month \ (ex: \ 9 = September) \end{array}$

| / | | | | | | | | | | | | |
|-------|------|-----|------|------|-------|------|-----|------|-------|------|------|------|
| Year | 2007 | ~ | 2016 | 2017 | 7 201 | 8 20 | 019 | 2020 | 2021 | 2022 | 2023 | 2024 |
| Code | U | ~ | D | E | F | | G | Н | I | J | K | L |
| Month | Jan | Feb | Mar | Apr | Мау | Jun | Jul | Aug | j Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | Ν | D |



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|------------------------|------------------|-------|------|
| Drain-Source Voltage | V _{DSS} | -20 | V |
| Gate-Source Voltage | V _{GSS} | ±8 | V |
| Drain Current (Note 5) | ID | -550 | mA |
| Pulsed Drain Current | I _{DM} | -1.9 | A |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|--------------------------------------------------|----------------------------------|-------------|------|
| | Synbol | value | Unit |
| Total Power Dissipation (Note 5) | PD | 500 | mW |
| Thermal Resistance, Junction to Ambient (Note 5) | R _{0JA} | 250 | °C/W |
| Operating and Storage Temperature Range | T _{J,} T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

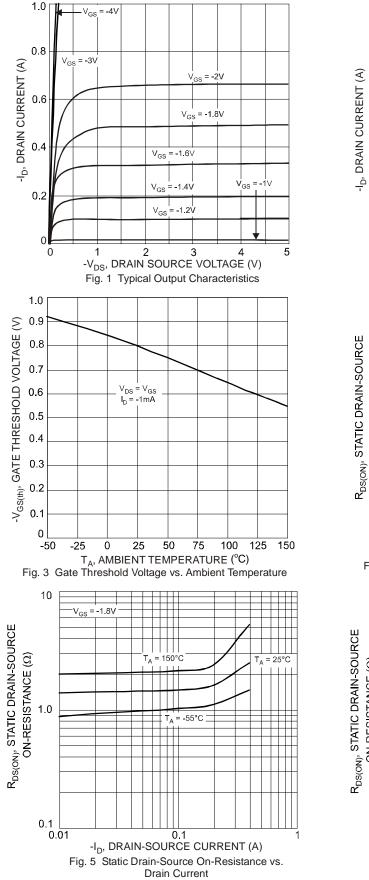
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|-----------------------------------|----------------------|------|------------|------------|------|------------------------------------------------|--|
| OFF CHARACTERISTICS (Note 6) | · · | | | | • | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | -20 | | _ | V | $V_{GS} = 0V, I_D = -250 \mu A$ | |
| Zero Gate Voltage Drain Current | I _{DSS} | _ | — | -1.0 | μΑ | $V_{DS} = -20V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±1.0 | μΑ | $V_{GS} = \pm 4.5 V$, $V_{DS} = 0 V$ | |
| ON CHARACTERISTICS (Note 6) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | -0.5 | | -1.0 | V | $V_{DS} = V_{GS}, I_D = -250 \mu A$ | |
| | | | 0.7 | 0.9 | | $V_{GS} = -4.5V, I_D = -430mA$ | |
| Static Drain-Source On-Resistance | R _{DS (ON)} | — | 1.1 1.7 | 1.4 2.0 | Ω | $V_{GS} = -2.5V, I_D = -300mA$ | |
| | | | | | | $V_{GS} = -1.8V, I_D = -150mA$ | |
| Forward Transfer Admittance | Y _{fs} | 200 | | _ | mS | V _{DS} = -10V, I _D = -0.2A | |
| Diode Forward Voltage (Note 6) | V _{SD} | -0.5 | | -1.2 | V | $V_{GS} = 0V, I_{S} = 115mA$ | |
| DYNAMIC CHARACTERISTICS | | | | | • | - | |
| Input Capacitance | C _{iss} | _ | | 175 | pF | | |
| Output Capacitance | C _{oss} | _ | | 30 | pF | $V_{DS} = -16V, V_{GS} = 0V$ | |
| Reverse Transfer Capacitance | Crss | _ | | 20 | pF | f = 1.0MHz | |

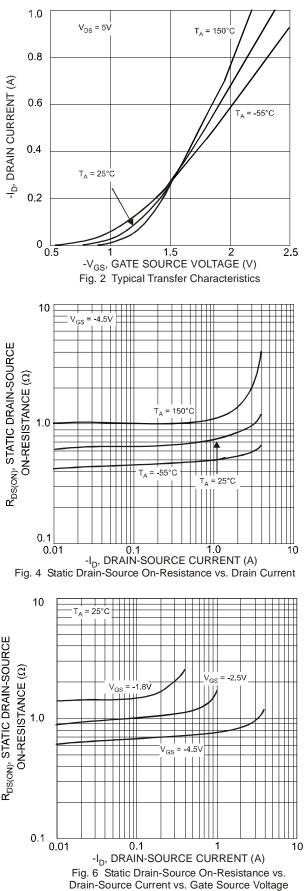
Notes:

Device mounted on FR-4 PCB.
Short duration pulse test used to minimize self-heating effect.



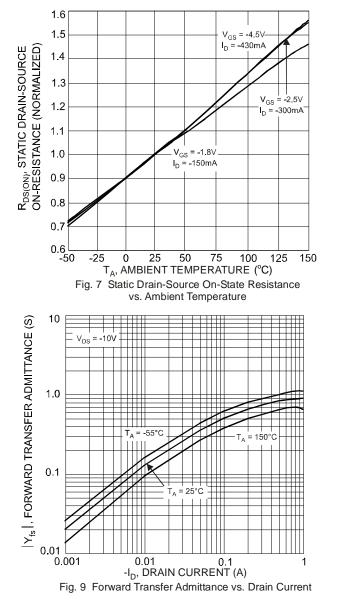
DMP2004DMK







DMP2004DMK



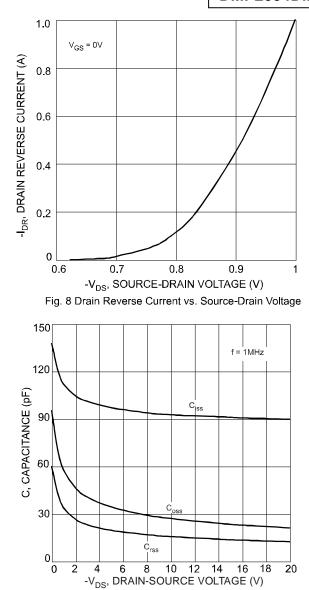
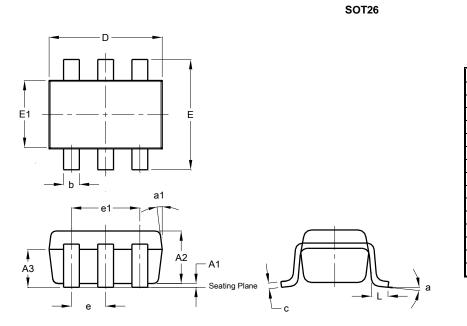


Fig. 10 Typical Capacitance



Package Outline Dimensions

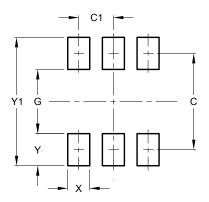
Please see http://www.diodes.com/package-outlines.html for the latest version.



| SOT26 | | | | | | |
|-------|-------|-------|-------|--|--|--|
| Dim | Min | Max | Тур | | | |
| A1 | 0.013 | 0.10 | 0.05 | | | |
| A2 | 1.00 | 1.30 | 1.10 | | | |
| A3 | 0.70 | 0.80 | 0.75 | | | |
| b | 0.35 | 0.50 | 0.38 | | | |
| c | 0.10 | 0.20 | 0.15 | | | |
| D | 2.90 | 3.10 | 3.00 | | | |
| е | - | - | .95 | | | |
| e1 | - | - | 1.90 | | | |
| ш | 2.70 | 3.00 | 2.80 | | | |
| E1 | 1.50 | 1.70 | 1.60 | | | |
| L | 0.35 | 0.55 | 0.40 | | | |
| а | - | - | 8° | | | |
| a1 | - | - | 7° | | | |
| All | Dimen | sions | in mm | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT26

| Dimensions | Value (in mm) |
|------------|---------------|
| С | 2.40 |
| C1 | 0.95 |
| G | 1.60 |
| Х | 0.55 |
| Y | 0.80 |
| Y1 | 3.20 |



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